

CLAIMS

1. A prewetted cleaning wipe for cleaning surfaces and having low volatile organic chemical and low nonvolatile residue properties comprising a wipe substrate wetted with an aqueous solution of water and an effective amount of an acetylenic alcohol surface active agent.
- 5
2. The cleaning wipe of Claim 1 wherein the surface active agent is an acetylenic diol.
- 10 3. The cleaning wipe of Claim 1 wherein the surface active agent is present in the range of 0.001% to 0.5% by weight.
- 15 4. The cleaning wipe of Claim 1 wherein the surface active agent is present in the range of 0.01% to 0.3% by weight.
- 15 5. The cleaning wipe of Claim 1 wherein the ratio of surface active agent is present in the range of 0.05% to 0.2% by weight.
- 20 6. The cleaning wipe of Claim 1 wherein the low volatile organic chemical property of the surface active agent is a vapor pressure of at least 1×10^{-4} torr at 25°C.
7. The cleaning wipe of Claim 4 wherein the low nonvolatile residue property of surface active agent is a vapor pressure of at least 1×10^{-3} torr at 25°C.

8. The cleaning wipe of Claim 1 wherein the surface active agent is dimethyl octynediol.

9. The cleaning wipe of Claim 1 wherein the surface active agent is
5 tetramethyl decynediol.

10. The cleaning wipe of Claim 1 wherein the wipe substrate is selected from
the group consisting of: cotton, abaca, polyester, nylon, polyester/cellulose, rayon,
polypropylene, rayon/polyester, polypropylene/cellulose, polyurethane, cotton/polyester
10 and mixtures thereof.

11. The cleaning wipe of Claim 1 wherein the surface active agent is selected
from the group consisting of: dimethyl octynediol; tetramethyl decynediol; 2,6,9,13-
tetramethyl-2,12-tetradecadien-7-yne-6-9-diol; 2,6,9-trimethyl-2-decen-7-yne-6-9-diol;;
15 7,10-dimethyl-8-hexadecyne-7,10-diol; 2,4,7,9-tetramethyl-5-decyne-4,7-diol; 4,7-
dimethyl-5-decyne-4,7-diol; 3,6-diethyl-4-octyne-3,6-diol; 2,5-dicycloprpyl-3-hexyne-2,5-
diol; 2,5-diphenyl-3-hexyne-2,5-diol; 2,5,8,11-tetramethyl-6-dodecyne-5,8-diol.and
mixtures thereof.

20 12. The cleaning wipe of Claim 1 wherein the ratio of surface active agent to
water is in the range of approximately 0.001% to 0.5% by weight.

13. The cleaning wipe of Claim 1 wherein the wipe substrate is a fibrous
substrate.

14. The cleaning wipe of Claim 1 wherein the wipe substrate is a woven
fibrous substrate.

15. The cleaning wipe of Claim 1 wherein the wipe substrate is a nonwoven
5 fibrous substrate.

16. The cleaning wipe of Claim 1 wherein the wipe substrate is a sponge.

17. The cleaning wipe of Claim 1 wherein the water is high purity water.

10
18. The cleaning wipe of Claim 1 wherein the water is deionized water.

15
19. The cleaning wipe of Claim 1 wherein the water is distilled water.

20. A prewetted cleaning wipe for cleaning surfaces in an electronic materials
fabricating area having a low volatile organic chemical content in the range of 0.001% to
0.5% by weight and low nonvolatile residue property of at least 1×10^{-4} torr at 25°C
comprising; a woven fibrous polyester/cellulose wipe substrate wetted with an aqueous
solution of high purity water selected from the group consisting of distilled water and
deionized water, and an effective amount of an acetylenic diol surface active agent
selected from the group consisting of dimethyl octynediol, tetramethyl decynediol and
mixtures thereof.

25
21. The cleaning wipe of Claim 20 wherein the surface active agent is in the
range of approximately 0.01% to 0.3% by weight.

22. The cleaning wipe of Claim 20 wherein the surface active agent is in the range of approximately 0.05% to 0.2% by weight.

5

N:\5918P\5918 P2 USA.doc